

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A semiconductor device comprising:
~~an antenna configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;~~
~~an integrated circuit comprising a thin film transistor;~~
~~a light-receiving element configured to receive a second optical signal; and~~
~~a light-emitting element configured to transmit a third optical signal,~~
wherein the light-emitting element and the light-receiving element each have a layer for conducting photoelectric conversion using a non-single crystal thin film, and
wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit on the same substrate.
2. (Currently Amended) A semiconductor device comprising:
~~an antenna configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;~~
~~an integrated circuit comprising a thin film transistor;~~
~~a light-receiving element configured to receive a second optical signal; and~~
~~a light-emitting element configured to transmit a third optical signal,~~
wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, and
wherein the integrated circuit, the light-emitting element and the light-receiving element are formed integrally on the same substrate.
3. (Currently Amended) A semiconductor device comprising:

an antenna ~~configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;~~

an integrated circuit comprising a thin film transistor;

a light-receiving element ~~configured to receive a second optical signal; and~~

a light-emitting element ~~configured to transmit a third optical signal,~~

wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, and

wherein the antenna, the integrated circuit, the light-emitting element and the light-receiving element are formed integrally on the same substrate.

4. (Currently Amended) A semiconductor device comprising:

an integrated circuit;

a light-receiving element ~~configured to receive a first optical signal; and~~

a light-emitting element ~~configured to transmit a second optical signal,~~

wherein the integrated circuit comprises a connection terminal, a rectification circuit that generates power supply voltage from an alternating current signal that is input to the connection terminal by an antenna, a demodulation circuit ~~for demodulating the first optical signal received in the light receiving element, and a logic circuit that conducts arithmetic operation according to the first optical signal that is demodulated to generate a third signal, and~~

~~wherein the light emitting element converts the third signal to the second optical signal, and~~

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed integrally on the same substrate.

5. (Currently Amended) A semiconductor device comprising:

an antenna ~~configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;~~

an integrated circuit comprising a thin film transistor;
a light-receiving element ~~configured to receive a second optical signal~~; and
a light-emitting element ~~configured to transmit a third optical signal~~,
wherein the light-emitting element and the light-receiving element each have a
layer for conducting photoelectric conversion using a non-single crystal thin film,
wherein the antenna, the light-emitting element and the light-receiving element
are electrically connected to the integrated circuit, [[and]]
wherein the integrated circuit, the light-emitting element and the light-receiving
element are formed over a first substrate and then separated therefrom, and attached to
a second substrate, and
wherein the integrated circuit, the light-emitting element and the light-receiving
element are formed on the second substrate.

6. (Currently Amended) A semiconductor device comprising:
~~an antenna configured to receive a first signal, wherein a power supply voltage is
generated based on the first signal;~~
an integrated circuit comprising a thin film transistor;
a light-receiving element ~~configured to receive a second optical signal~~; and
a light-emitting element ~~configured to transmit a third optical signal~~,
wherein the antenna, the light-emitting element and the light-receiving element
are electrically connected to the integrated circuit, [[and]]
wherein the integrated circuit, the light-emitting element and the light-receiving
element are formed over a first substrate and then separated therefrom, and attached to
a second substrate, and
wherein the integrated circuit, the light-emitting element and the light-receiving
element are formed on the second substrate.

7. (Currently Amended) A semiconductor device comprising:

~~an antenna configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;~~

an integrated circuit comprising a thin film transistor;

~~a light-receiving element configured to receive a second optical signal; and~~

~~a light-emitting element configured to transmit a third optical signal,~~

wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, [[and]]

wherein the antenna, the integrated circuit, the light-emitting element and the light-receiving element are formed over a first substrate and then separated therefrom, and attached to a second substrate, and

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed on the second substrate.

8. (Currently Amended) A semiconductor device comprising:

an integrated circuit;

~~a light-receiving element configured to receive a first optical signal; and~~

~~a light-emitting element configured to transmit a second optical signal,~~

wherein the integrated circuit comprises a connection terminal, a rectification circuit that generates power supply voltage from an alternating current signal that is input to the connection terminal by an antenna, a demodulation circuit for demodulating the first optical signal received in the light receiving element, and a logic circuit that conducts arithmetic operation according to the first optical signal that is demodulated to generate a third signal,

~~wherein the light emitting element converts the third signal to the second optical signal,~~

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed integrally, [[and]]

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed over a first substrate and then separated therefrom, and attached to a second substrate, and

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed on the second substrate.

9. (Currently Amended) [[A]] The semiconductor device according to any one of Claims 5 to 8, wherein the first substrate is a glass substrate and the second substrate is a plastic substrate.

10. (Currently Amended) An IC card comprising:

~~an antenna configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;~~

~~an integrated circuit comprising a thin film transistor;~~

~~a light-receiving element configured to receive a second optical signal; and~~

~~a light-emitting element configured to transmit a third optical signal,~~

wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, and

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed integrally on the same substrate.

11. (Currently Amended) [[An]] The IC card according to claim 10, wherein the antenna, the integrated circuit, the light-emitting element and the light-receiving element are formed integrally on the same substrate.

12. (Currently Amended) An IC card comprising:

~~an integrated circuit;~~

~~a light-receiving element configured to receive a first optical signal; and~~

~~a light-emitting element configured to transmit a second optical signal, wherein the integrated circuit comprises a connection terminal, a rectification circuit that generates power supply voltage from an alternating current signal that is input to the connection terminal by an antenna, a demodulation circuit for demodulating the first optical signal received in the light-receiving element, and a logic circuit that conducts arithmetic operation according to the first optical signal that is demodulated to generate a third signal, and~~

~~wherein the light-emitting element converts the third signal to the second optical signal, and~~

~~wherein the integrated circuit, the light-emitting element and the light-receiving element are formed integrally on the same substrate.~~

13. (Currently Amended) An IC card comprising:

~~an antenna configured to receive a first signal, wherein a power supply voltage is generated based on the first signal;~~

~~an integrated circuit comprising a thin film transistor;~~

~~a light-receiving element configured to receive a second optical signal; and~~

~~a light-emitting element configured to transmit a third optical signal,~~

~~wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, [[and]]~~

~~wherein the integrated circuit, the light-emitting element and the light-receiving element are formed over a first substrate and then separated therefrom, and attached to a second substrate, and~~

~~wherein the integrated circuit, the light-emitting element and the light-receiving element are formed on the second substrate.~~

14. (Currently Amended) [[An]] The IC card according to claim 13, wherein the antenna and the integrated circuit in addition to the light-emitting element and the light-

receiving element are formed over the first substrate and then separated therefrom, and attached to the second substrate.

15. (Currently Amended) [[An]] The IC card according to claim 12, wherein the integrated circuit, the light-emitting element and the light-receiving element are formed over a first substrate and then separated therefrom, and attached to a second substrate.

16. (Original) The IC card according to any one of Claims 13 to 15, wherein the first substrate is a glass substrate and the second substrate is a plastic substrate.